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January 13, 2017

VIEWPOINT 2017: Marco Notarianni, Ph.D., Platform Manager, Singulator®

Plasma-Therm® is a leading provider of advanced plasma processing equipment that has won "RANKED 1st" awards every year since 2012 from the VLSIresearch Customer Satisfaction Survey.

Plasma-Therm systems perform critical process steps in the fabrication of integrated circuits, micro-mechanical devices, compound semiconductors, and other components of products ranging from consumer electronics to military systems and space satellites. Specifically, Plasma-Therm systems employ innovative plasma technology to etch and deposit thin films.

The acquisitions of Nano Etch Systems (NES) Inc. of California, a developer of ion beam etch (IBE) and ion beam deposition (IBD) systems, and Nanoplas, a developer of low-temperature, low-damage surface preparation and stripping systems, significantly expanded Plasma-Therm's portfolio in the etch and deposition business.

The superior performance of these systems, coupled with Plasma-Therm's award-winning customer service, make a compelling value proposition for manufacturers in data storage, MEMS, wireless, photonics, and other markets.

In 2016, Plasma-Therm reached an important milestone in serving the advanced packaging industry with the signing of a global distribution agreement with DISCO, the leader in Dicing, Grinding, and Polishing (Kiru, Kezuru and Migaku) technologies. Plasma-Therm's Singulator® plasma dicing platform delivers superior dicing quality, productivity and design



Marco Notarianni,
Ph.D., Platform
Manager, Singulator®

Everything-Proof Mobile Devices

Consumers have turned their focus to durability. Resistance to drops, harsh environments and, yes, water submersion are the new expectations for next-generation devices. Can it be achieved?
Henkel Electronic Materials, LLC



First to Market pH Neutral Solutions

ZESTRON's true pH neutral defluxing solutions offer superior material compatibility for power electronics, VIGON® PE 180 and semiconductor, HYDRON® SE 220.
ZESTRON



Hybrid - FC and Passives Placement

The Hybrid -- a true modular system combining FC bonding with accuracy up to 7µm and possible 27K CPH for FC or 120K CPH for passives parts -- is the best solution for many applications.
Kulicke & Soffa



freedom to the advanced packaging market.

The shipment of a 300mm Singulator® system to DISCO's R&D center in Tokyo in early 2017, along with increasing interest from OSATs and IDMs, demonstrates that the shift to plasma dicing technology is now underway.

Marco Notarianni, Ph.D., Platform Manager
Singulator®

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